# **LNA2W01L** (LN57)

### GaAs Infrared Light Emitting Diode

For optical control systems

#### ■ Features

- High-power output, high-efficiency:  $P_O = 4.5 \text{ mW (typ.)}$
- Emitted light spectrum suited for silicon photodetectors
- Infrared light emission close to monochromatic light:  $\lambda_P = 950$  nm (typ.)
- Wide directivity:  $\theta = 18^{\circ}$  (typ.)
- Ultra-miniature double ended package

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	75	mW	
Forward current	I <sub>F</sub>	50	mA	
Pulse forward current *	$I_{FP}$	1	A	
Reverse voltage	$V_R$	3	V	
Operating ambient temperature	T <sub>opr</sub>	-25 to +85	°C	
Storage temperature	T <sub>stg</sub>	-30 to +100	°C	

Note) \*: f = 100 Hz, Duty cycle = 0.1%

#### ■ Electrical-Optical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Radiant power *	$P_{O}$	$I_F = 50 \text{ mA}$	3.0	4.5	3	mW
Reverse current	$I_R$	$V_R = 3 V$			10	μА
Forward voltage	$V_{\rm F}$	$I_F = 50 \text{ mA}$		1.25	1.50	V
Terminal capacitance	$C_{t}$	$V_R = 0 V, f = 1 MHz$	2000	35		pF
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 50 \text{ mA}$	χ'	950		nm
Spectral half band width	Δλ	$I_F = 50 \text{ mA}$		50		nm
Half-power angle	θ	The angle when the radiant power is halved.		18		0

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

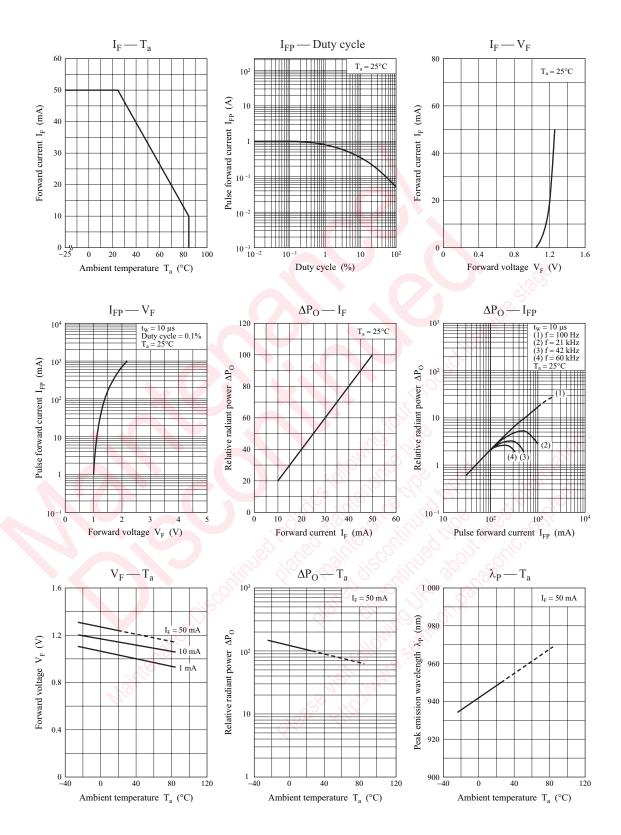
2. Cutoff frequency: 1 MHz

$$f_C: 10 \times \log \frac{P_O \text{ at } f = f_C}{P_O \text{ at } f = 50 \text{ kHz}} = -3$$

3. \*: A light detection element uses a silicon diode have proofread a load with a standard device.

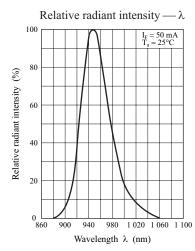
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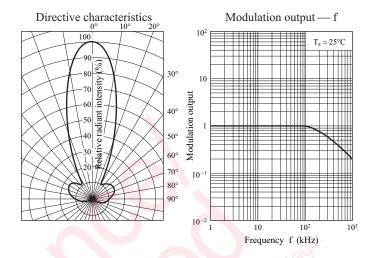
### **Panasonic**



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Panasonic LNA2W01L

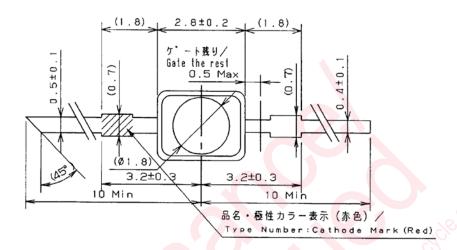


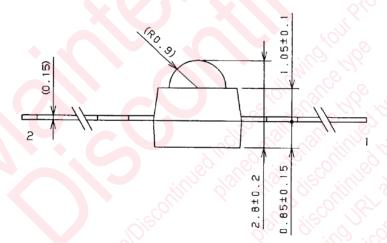


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■ Package (Unit: mm)

## LETLTN2S0001







- Pin name
  - 1: Anode
  - 2: Cathode

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